



SOT765-1

plastic, very thin shrink small outline package; 8 leads; 0.5 mm pitch; 2 mm x 2.3 mm x 1 mm body

30 January 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	VSSOP8
Package type industry code	VSSOP8
Package style descriptive code	VSSOP (very thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-187
Mounting method type	S (surface mount)
Issue date	31-5-2016
Manufacturer package code	SOT765

Table 1. Package summary

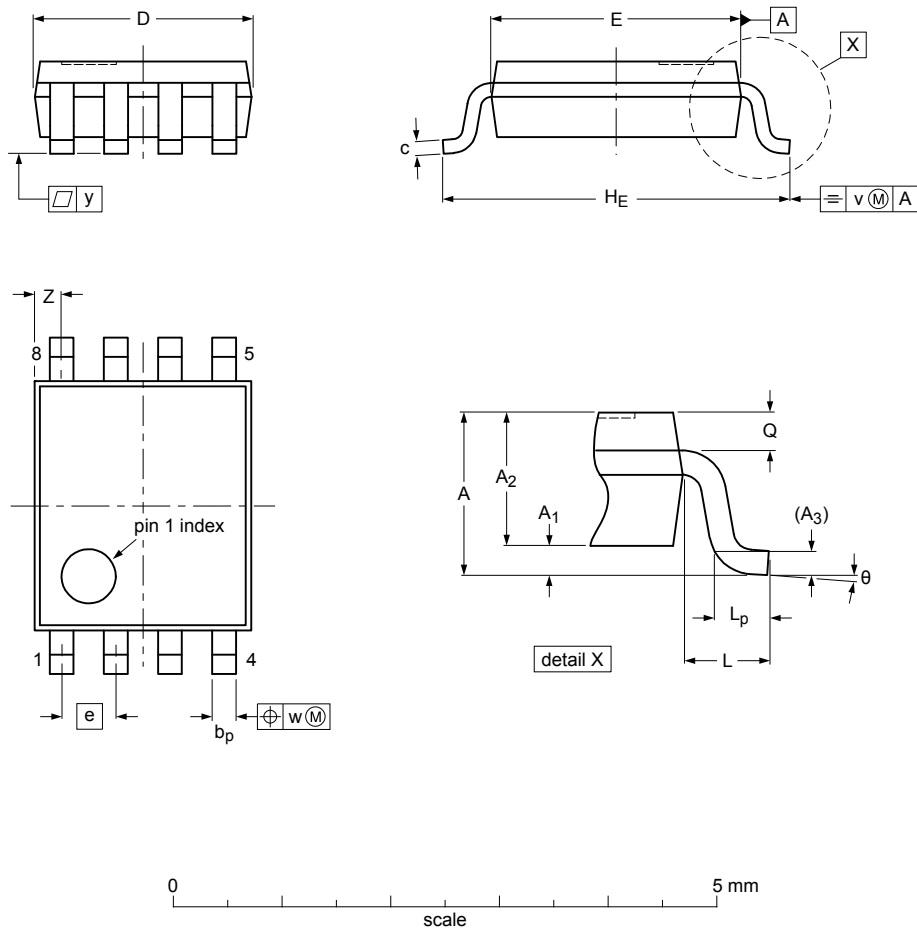
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.2	-	2.3	2.4	mm
A	seated height	-	-	1	1	mm
A ₂	package height	0.6	-	0.75	0.85	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	8	-	

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2. Package outline

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

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Dimensions (mm are the original dimensions)

Unit	A _{max.}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	max	0.15	0.85		0.27	0.23	2.1	2.4	0.5	3.2	0.4	0.40	0.21		0.08	0.1	0.4	8°
	nom	1		0.12										0.2				
	min		0.00	0.60	0.17	0.08	1.9	2.2		3.0	0.15	0.19					0.1	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot765-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT765-1		MO-187			-07-06-02-16-05-31

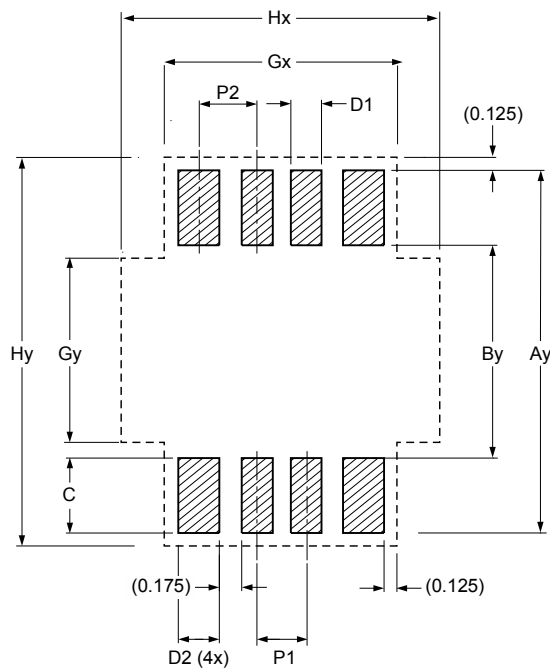
Fig. 1. Package outline VSSOP8 (SOT765-1)

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3. Soldering

Footprint information for reflow soldering of VSSOP8 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land

----- occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.550	3.500	2.000	0.750	0.300	0.400	2.250	1.750	3.075	3.750

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Fig. 2. Reflow soldering footprint for VSSOP8 (SOT765-1)

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4. Legal information

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